



## Material Content Data Sheet



<b>Sales Product Name</b>	TLS850D0TE V33			<b>Issued</b>	23. January 2018			
<b>MA#</b>	MA001489794							
<b>Package</b>	PG-TO252-5-11			<b>Weight*</b>	363.83 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.503	0.69	0.69	6879	6879
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		169	
	non noble metal	iron	7439-89-6	0.205	0.06		562	
wire	non noble metal	copper	7440-50-8	204.243	56.13	56.21	561377	562108
	non noble metal	aluminium	7429-90-5	0.207	0.06	0.06	568	568
encapsulation	organic material	carbon black	1333-86-4	0.298	0.08		820	
	plastics	epoxy resin	-	13.726	3.77		37726	
	inorganic material	silicondioxide	60676-86-0	135.167	37.15	41.00	371516	410062
leadfinish	non noble metal	tin	7440-31-5	5.072	1.39	1.39	13942	13942
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	209	210
solder	non noble metal	tin	7440-31-5	0.045	0.01		125	
	noble metal	silver	7440-22-4	0.057	0.02		156	
	non noble metal	lead	7439-92-1	2.165	0.60	0.63	5950	6231
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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